

REMARKS

This responds to the Office Action mailed on November 10, 2004.

Claims 13-15 and 17 are amended, claims 21-23 are canceled, and claim 25 is added; as a result, claims 1-20 and 24-25 are now pending in this application.

Double Patenting Rejection

Claim 16 was provisionally rejected under the judicially created doctrine of obviousness-type double patenting as being unpatentable over claims 21 and 22 of co-pending Application No. 10/071,743.

The Applicant reserves the right to take action regarding this matter in the future.

§102 Rejection of the Claims

Claims 1-20 and 24 were rejected under 35 USC § 102(e) as being anticipated by Jayaraman et al. (U.S.2003/0153667).

The Examiner has rejected claims 1-20 and 24 as being anticipated by US 2003/0153667('667). However, paragraph 25 of the '667 reference describes the "non-fusible filler particles 402" (shown in FIG. 4A) and the "fusible filler 403." Figure 4A shows a non-fusible particle 402 that is much larger than fusible filler 403. This teaching is contrary to what is claimed in claims 1-20 and 24..

The Examiner cites paragraph 28 as supporting the assertion of anticipation. However, paragraph 28 does not discuss particle size at all. Particle weights are described. There is no correspondence between particle weight and particle size that is provided in the reference. The mention of particle size in the '667 patent application teach a relationship which is contrary to what is described in the present application.

Serial Number: 10/612,328

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Filing Date: June 30, 2003

Title: POLYMER SOLDER HYBRID INTERFACE MATERIAL WITH IMPROVED SOLDER FILLER PARTICLE SIZE AND MICROELECTRONIC PACKAGE APPLICATION

Assignee: Intel Corporation

Conclusion

Applicant respectfully submits that the claims are in condition for allowance and notification to that effect is earnestly requested. The Examiner is invited to telephone Applicant's attorney ((612) 373-6976) to facilitate prosecution of this application.

If necessary, please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

Respectfully submitted,

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By their Representatives,

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Date 10 June 05

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CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this 10th day of January, 2005.

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Name

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